# Seonho Seok

List of Publications by Year
in descending order

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|---|---|---|---|
| 16<br>papers | 201<br>citations | 1307594<br>7<br>h-index | 1199594<br>12<br>g-index |
| 16<br>all docs | 16<br>docs citations | 16<br>times ranked | 135<br>citing authors |

| # | Article | IF | Citations |
|---|---|---|---|
| 1 | Scotch-tape surface wrinkling based thin-film material properties extraction. Journal of Micromechanics and Microengineering, 2022, 32, 045002. | 2.6 | 2 |
| 2 | A Study on Biocompatible Polymer-Based Packaging of Neural Interface for Chronic Implantation. Micromachines, 2022, 13, 516. | 2.9 | 6 |
| 3 | Editorial for the Special Issue â€œMEMS Packaging Technologies and 3D Integrationâ€. Micromachines, 2022, 13, 749. | 2.9 | 1 |
| 4 | Experiment and analysis of the effect of BCB sealing ring flatness on BCB cap transfer packaging. Microsystem Technologies, 2021, 27, 263-268. | 2.0 | 2 |
| 5 | Polymer-Based Biocompatible Packaging for Implantable Devices: Packaging Method, Materials, and Reliability Simulation. Micromachines, 2021, 12, 1020. | 2.9 | 15 |
| 6 | Characterization and Analysis of Metal Adhesion to Parylene Polymer Substrate Using Scotch Tape Test for Peripheral Neural Probe. Micromachines, 2020, 11, 605. | 2.9 | 10 |
| 7 | Analysis of Thin Film Parylene-Metal-Parylene Device Based on Mechanical Tensile Strength Measurement. , 2019, , . | | 1 |
| 8 | Overview of MEMS Packaging Technologies. Springer Series in Advanced Manufacturing, 2018, , 1-12. | 0.5 | 6 |
| 9 | FEM Modeling of Debonding of Transfer Packaging. Springer Series in Advanced Manufacturing, 2018, , 83-101. | 0.5 | 0 |
| 10 | Buckled Thin Film Cap Transfer Packaging Technology. Springer Series in Advanced Manufacturing, 2018, , 67-81. | 0.5 | 0 |
| 11 | Fabrication and Modeling of Nitride Thin-Film Encapsulation Based on Anti-Adhesion-Assisted Transfer Technique and Nitride/BCB Bilayer Wrinkling. IEEE Transactions on Components, Packaging and Manufacturing Technology, 2016, 6, 1301-1307. | 2.5 | 11 |
| 12 | Enhancement of bonding strength of packaging based on BCB bonding for RF devices. Microsystem Technologies, 2012, 18, 2035-2039. | 2.0 | 9 |
| 13 | Polymer-based zero-level packaging technology for high frequency RF applications by wafer bonding/debonding technique using an anti-adhesion layer. International Journal of Precision Engineering and Manufacturing, 2012, 13, 1861-1867. | 2.2 | 10 |
| 14 | A theoretical and experimental study of the BCB thin-film cap zero-level package based on FEM simulations. Journal of Micromechanics and Microengineering, 2010, 20, 095010. | 2.6 | 8 |
| 15 | A study on wafer level vacuum packaging for MEMS devices. Journal of Micromechanics and Microengineering, 2003, 13, 663-669. | 2.6 | 120 |
| 16 | Scotch-Tape Surface Wrinkling Based Thin-Film Material Properties Extraction. Journal of Micromechanics and Microengineering, 0, , . | 2.6 | 0 |